

Claims for Patent application #10/803,626 rewritten/re-ordered such that they identify a single embodiment of the invention: A robust modular electronic device without direct electrical connection or control. This is in response to a Restriction Requirement regarding this patent application. Inventor: Robert J. Rapp Customer #41400, rappj@sbglobal.net, 408-247-3304, 1120 Ranchero Way #10 San Jose, Ca 95117; Patent examiner Truc T. Nguyen (Art Unit 2833). *RSR 7-12-05*

Claims:

Claim 1:

A modular electronic device where non direct electrical contact (non-contact) mechanisms are used for inter-module communication, and where modules are attached forming an extendable structure with extendable function.

Claim 2:

A device as in Claim 1 where non-direct electrical contact control mechanisms are used.

Claim 3:

A device as in Claim 2 where alignment mechanisms and retention mechanisms are used to align and attach modules.

Claim 4:

A device as in Claim 3 where the modules are sealed, with electronics inside.

Claim 5:

A device as in Claim 4 where inter-module power is distributed using magnetic induction/transformer action.

Claim 6:

A device as in Claim 5 where an alignment mechanism is used as a transformer core.

Claim 7:

A device as in Claim 6 where modules are liquid filled for cooling electronics contained within.

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Claim 8:

A device as in Claim 6 where modules are liquid filled for withstanding a high pressure environment.

Claim 9:

A device as in Claim 4 where inter-module power is distributed using a non-contact power distribution mechanism.

Claim 10:

A device as in Claim 9 where alignment mechanisms are used to improve the efficiency of non-contact power distribution mechanisms.

Claim 11:

A device as in Claim 4 where alignment mechanisms are used to improve the efficiency of non-contact inter-module communication mechanisms.

Claim 12:

A system and method for extending the function of an electronic device where a plurality of modules as described in preceding claims are aligned and attached as the structure of the electronic device is extended.